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## Recent Advances in Soft Electronics and Ionics

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Deadline for manuscript  
submissions:

**closed (15 March 2020)**

### Message from the Guest Editor

Dear Colleagues,

As electronic devices are getting more and more integrated into our everyday activities, the need to minimize mechanical mismatch between electronic devices (rigid by nature) and biological systems (soft by nature) is becoming more eminent. There is a broad range of applications for soft, flexible, and stretchable electronic devices in a variety of fields of research, including biomedical, sensing, actuation, energy storage, energy harvesting, hardware security, military, athletics, and rehabilitation. The deformability of such electronic devices is, however, counterintuitive to the physical and dimensional stability that is required for the stable operation of electronic devices.

The ultimate goal of this Special Issue is to gather and disseminate the most innovative, impactful, and recent advances and discoveries in the field of soft electronic and ionic devices. Communications, full papers, and review papers are all welcome.



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# Special Issue



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## Message from the Editor-in-Chief

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